Response to Advisory Action Mailed October 23, 2002

**PATENT** 

#4/C 11/8/12 V

## Express Mail Number EV140162004US

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

David W. Carlson

Appln. No.: 09/678,414

Filed: October 2, 2000

For: METHOD FOR PLANARIZING A THIN

**FILM** 

Group Art Unit: 2823

Examiner: B. Kebede

RESPONSE TO ADVISORY ACTIO

MAILED OCTOBER 23, 2002

ROOM

Commissioner for Patents Washington, D.C. 20231

Dear Sir:

In response to the Advisory Action mailed October 23, 2002, please amend the above-identified application as follows:

## In the Claims

Claim 18 has been cancelled.

The claims have been amended to read as follows:

 $G_{I}$ 

- 16. (Amended) The method of claim 1 wherein the layer of first material makes an electrical contact with a device on the wafer.
- 19. (Amended) The method of claim 22 wherein the first lower level lies above the wafer upper level.
  - 20. (Amended) The method of claim 19

wherein the planarized layer of first material has a thickness over the wafer upper layer, and

Atty. Docket No.: 100-13601

(P04797-C1)